

LNPTM STAT-KONTM COMPOUND DE003Z

DC-1003 E

REGION AMERICAS

DESCRIPTION

LNP STAT-KON DE003Z compound is based on Polycarbonate (PC) resin containing 15% carbon fiber. Added features of this grade include: Electrically Conductive, Extrusion grade.

GENERAL INFORMATION	
Features	Electrically Conductive, Carbon fiber filled, High stiffness/Strength
Fillers	Carbon Fiber
Polymer Types	Polycarbonate (PC)
Processing Techniques	Injection Molding, Extrusion
INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components
Industrial	Material Handling

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yld, Type I, 5 mm/min	134	MPa	ASTM D638
Tensile Stress, brk, Type I, 5 mm/min	134	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	2.4	%	ASTM D638
Tensile Modulus, 5 mm/min	11320	MPa	ASTM D638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	200	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	9120	MPa	ASTM D790
Tensile Stress, break, 5 mm/min	130	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2.6	%	ISO 527
Tensile Modulus, 1 mm/min	10660	MPa	ISO 527
Flexural Stress	191	MPa	ISO 178
Flexural Modulus, 2 mm/min	9290	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	623	J/m	ASTM D4812
Izod Impact, notched, 23°C	98	J/m	ASTM D256
Multiaxial Impact	4	J	ISO 6603
Instrumented Dart Impact Total Energy, 23°C	24	J	ASTM D3763
Izod Impact, unnotched 80°10°4 +23°C	39	kJ/m ²	ISO 180/1U
Izod Impact, notched 80°10°4 +23°C	8	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 0.45 MPa, 3.2 mm, unannealed	147	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	144	°C	ASTM D648

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -30°C to 30°C, flow	2.2E-05	1/°C	ASTM D696
CTE, -30°C to 30°C, xflow	4.8E-05	1/°C	ASTM D696
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	147	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	143	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Specific Gravity	1.26	-	ASTM D792
Density	1.253	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.13	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.1 – 0.3	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.4 – 0.6	%	ASTM D955
Moisture Absorption (23°C / 50% RH)	0.21	%	ISO 62
INJECTION MOLDING ⁽³⁾			
Drying Temperature	120	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	305 – 325	°C	
Front - Zone 3 Temperature	320 – 330	°C	
Middle - Zone 2 Temperature	310 – 320	°C	
Rear - Zone 1 Temperature	295 – 305	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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